

DECLARATION OF SOLE INVENTOR FOR PATENT APPLICATION

1 As the below named inventor, I hereby declare that:

3 My residence, post office address and citizenship are as stated
4 below next to my name.

5 I believe I am the original, first and sole inventor of the subject
6 matter which is claimed and for which a patent is sought on the
7 invention entitled: Semiconductor Processing Methods of Forming a
8 Contact Opening to a Conductive Line and Methods of Forming
9 Substrate Active Area Source/Drain Regions, the specification of which
10 is attached hereto.

11 I hereby state that I have reviewed and understand the contents
12 of the above-identified specification, including the claims.

13 I acknowledge the duty to disclose information known to me to
14 be material to patentability as defined in Title 37, Code of Federal
15 Regulations §1.56.

16 **PRIOR FOREIGN APPLICATIONS:**

17 I hereby state that no applications for foreign patents or inventor's
18 certificates have been filed prior to the date of execution of this
19 declaration.

20 I hereby declare that all statements made herein of my own
21 knowledge are true and that all statements made on information and
22 belief are believed to be true; and further that these statements were
23 made with the knowledge that willful false statements and the like so
24 made are punishable by fine or imprisonment, or both, under

1 Section 1001 of Title 18 of the United States Code and that such willful
2 false statement may jeopardize the validity of the application or any
3 patent issued therefrom.

5 Full name of sole inventor: Werner Juengling

6 Inventor's Signature: Werner Muehling

Date: 24-Aug-98

8 Residence: **Boise, Idaho**

9 Citizenship: Austria/Europe

10 Post Office Address: 5660 S. Tecoma Place
Boise, ID 83705